

极限参数 / Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
Maximum RMS Voltage	V_{RMS}	420	V
Maximum DC Blocking Voltage	V_{DC}	600	V
Maximum Average Forward Current	$I_{(AV)}$	4×20	A
Peak forward surge current	I_{FSM}	180	A
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	2.2	°C/W
Junction Temperature Range	T_J	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R	$I_R=1mA$	600	680		V
Forward Voltage	V_F	$I_F=5A$ $T_C=25^\circ C$		1.28	1.45	V
		$I_F=5A$ $T_C=125^\circ C$		1.05	1.25	
		$I_F=10A$ $T_C=25^\circ C$		1.55	1.75	
		$I_F=10A$ $T_C=125^\circ C$		1.25	1.45	
		$I_F=20A$ $T_C=25^\circ C$		1.95	2.25	
		$I_F=20A$ $T_C=125^\circ C$		1.55	1.75	
Instantaneous Reverse Current	I_R (Note 1)	$V_R=600V$ $T_a=25^\circ C$			10	μA
		$V_R=600V$ $T_a=125^\circ C$			500	
Reverse Recovery Time	t_{rr}	$I_F=0.5A$ $I_R=1.0A$ $I_{RR}=0.25A$		35	50	ns

Notes:

1. 璃条
effect.

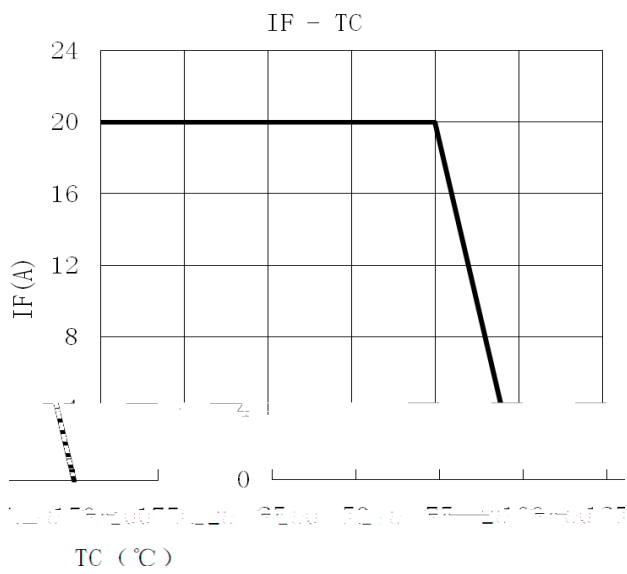
Short duration pulse test used to minimize self-heating

2. 片
single chip

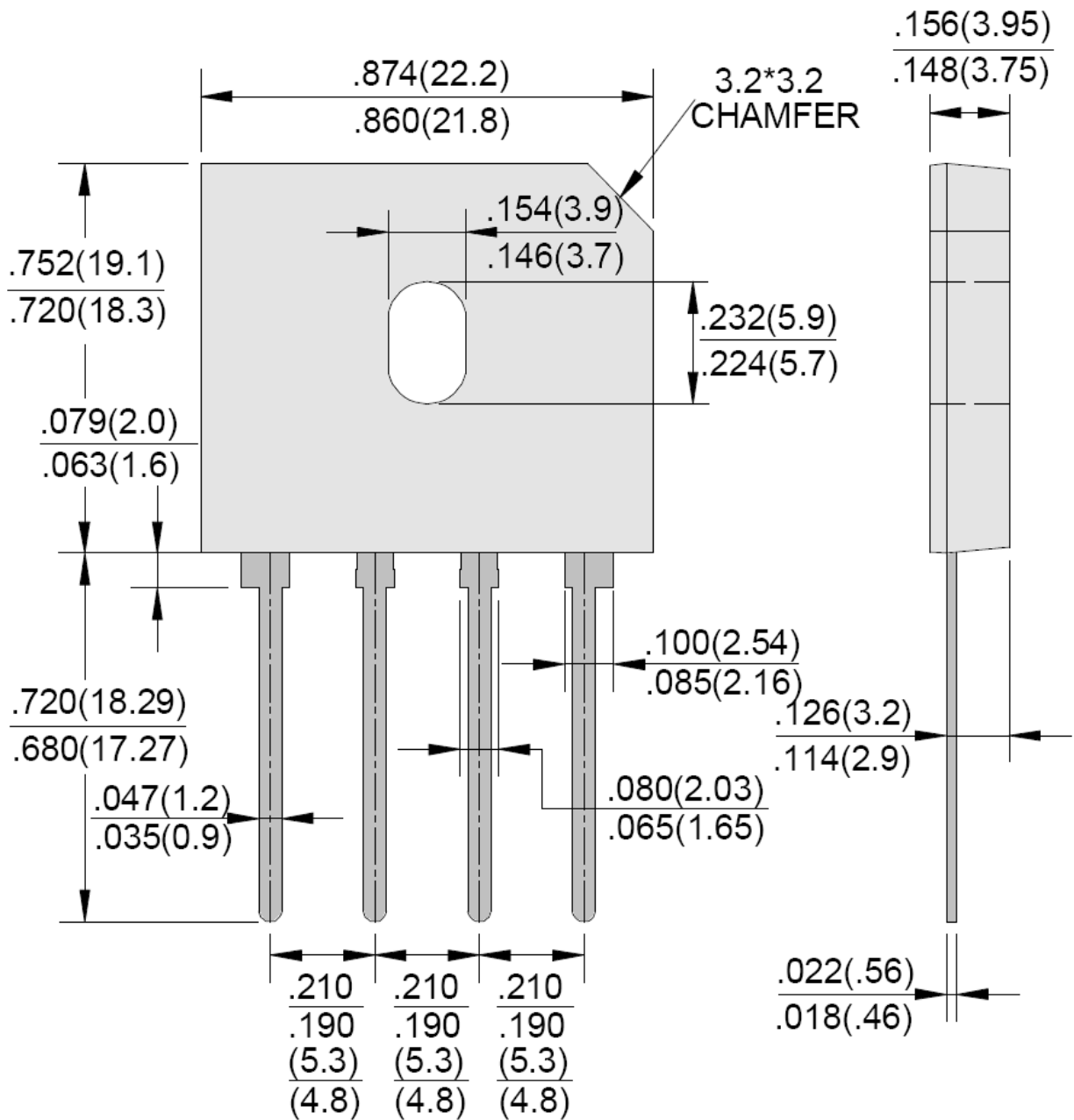
Unless otherwise noted, values for the parameters of a



电参数曲线图 / Electrical Characteristic Curve



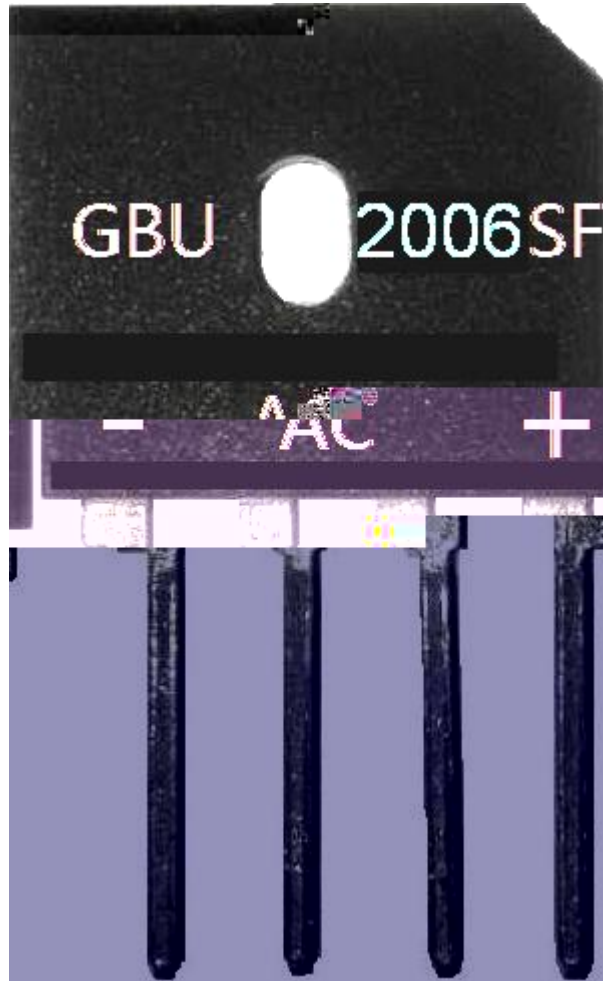
外形尺寸图 / Package Dimensions

GBU

Dimensions in inches and (millimeters)



印章说明 / Marking Instructions



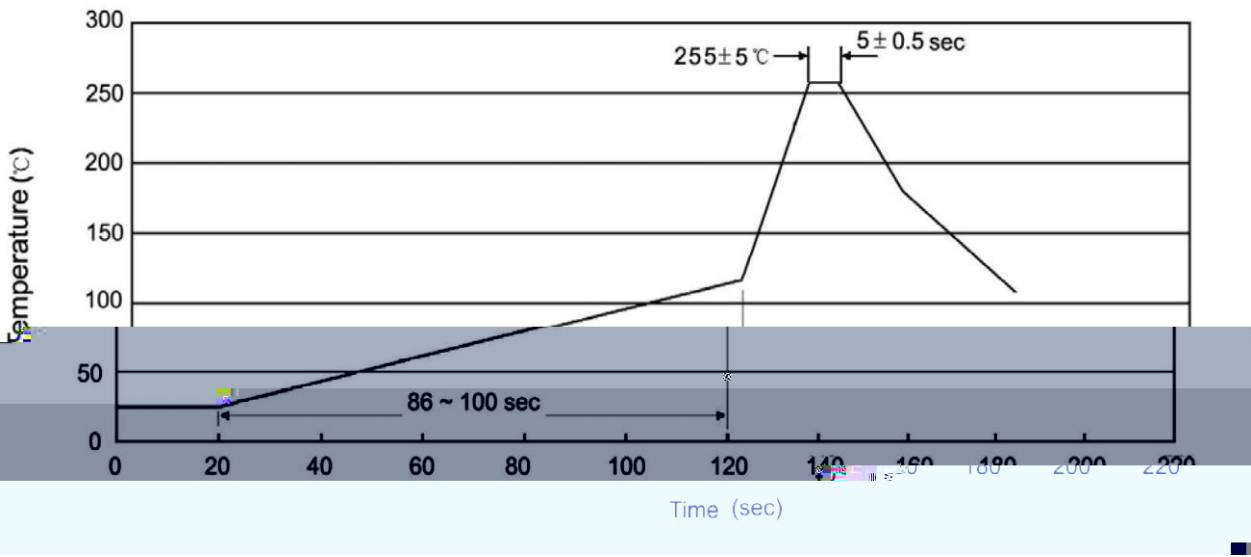
GBU2006SF

Note:

GBU2006SF

Product Type

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp.:270±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.